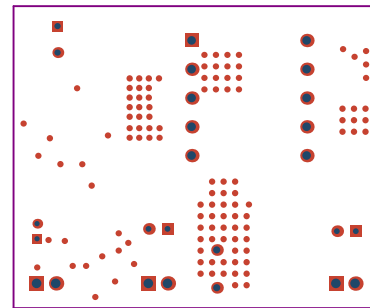
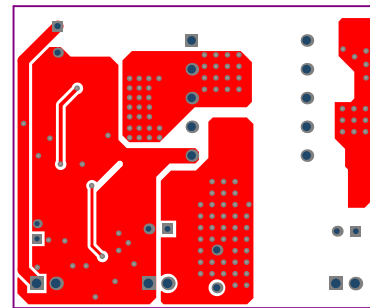


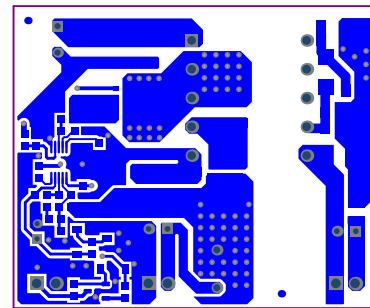
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00711	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00711		
PLOT NAME = Top Overlay	GENERATED : 12/9/2016	5:52:04 PM	TEXAS INSTRUMENTS



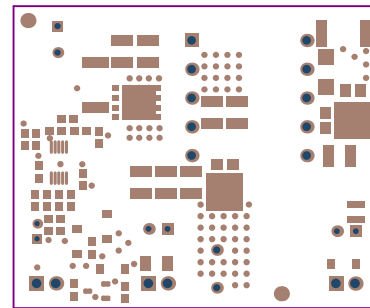
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00711	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00711		
PLOT NAME = Top Solder Mask	GENERATED : 12/9/2016 5:52:04 PM	TEXAS INSTRUMENTS	



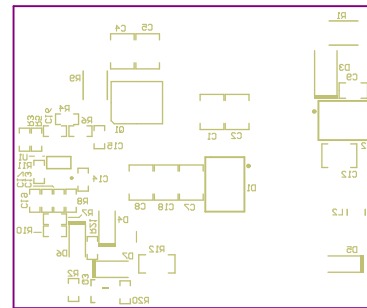
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00711	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00711		
PLOT NAME = Top Layer	GENERATED : 12/9/2016 5:52:05 PM	TEXAS INSTRUMENTS	



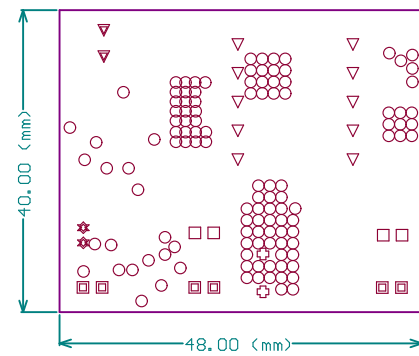
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00711	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00711		
PLOT NAME = Bottom Layer	GENERATED : 12/9/2016 5:52:05 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00711	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00711		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/9/2016 5:52:06 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00711	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00711		
PLOT NAME = Bottom Overlay	GENERATED : 12/9/2016 5:52:06 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
*	2	28.00mil (0.711mm)	PTH	Round
▽	2	33.46mil (0.850mm)	PTH	Round
⊗	2	37.40mil (0.950mm)	PTH	Round
□	4	31.00mil (0.787mm)	PTH	Round
■	6	51.18mil (1.300mm)	PTH	Round
▽	10	46.06mil (1.170mm)	PTH	Round
○	115	15.00mil (0.381mm)	PTH	Round
	<b>141 Total</b>			

DRILL TABLE  
 FOR 15MIL DRILL +0/-15MIL  
 FOR PTH +3/-3MIL  
 Copper thickness is 2oz.

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00711	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00711		
PLOT NAME = Drill Drawing	GENERATED : 12/9/2016 5:52:07 PM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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